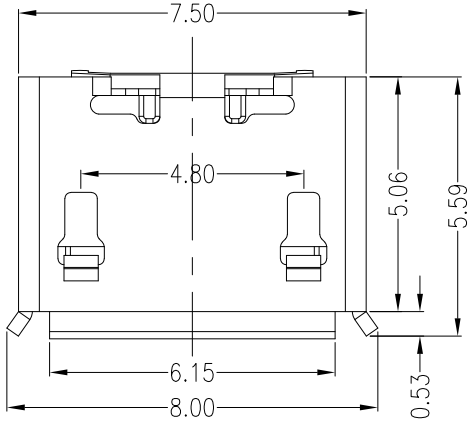
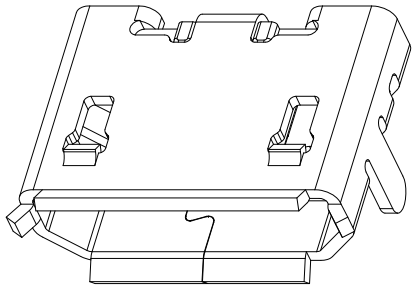
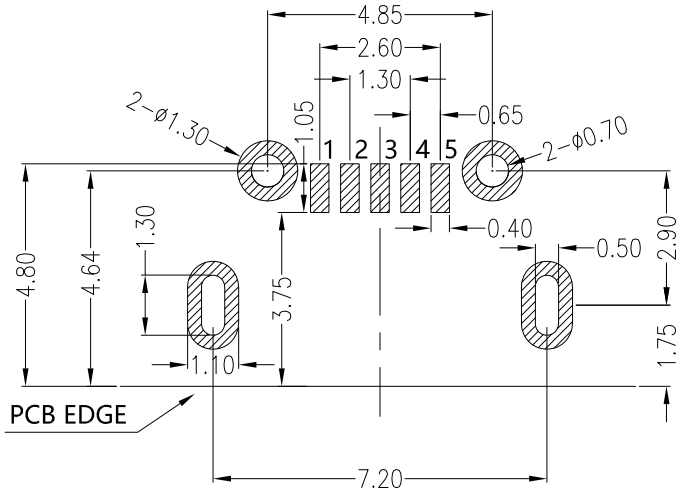
GP Component

REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
A0			Initial	2022/11/02	Ken Lni



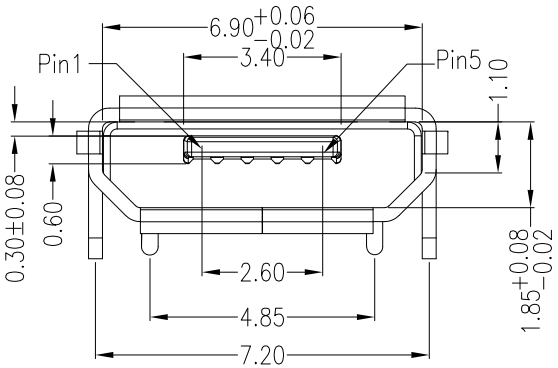


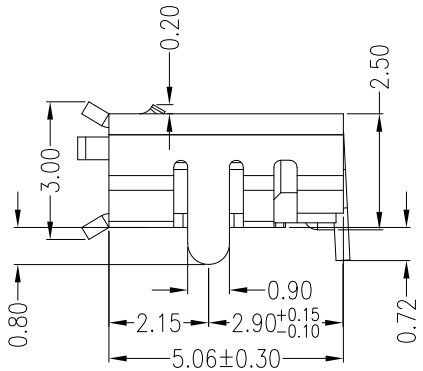
3D VIEW

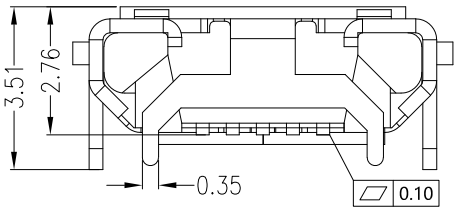


PCB Layout (TOP VIEW)

NOTE: GENERAL TOLERANCE: ±0.05mm







Note:

1.Material:

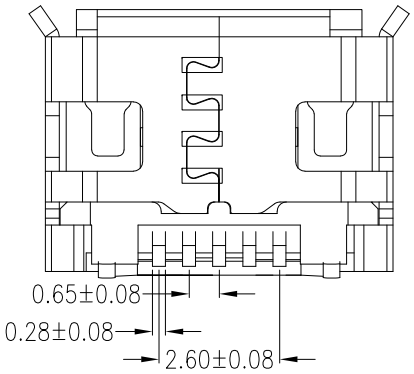
1.1 Housing: High temperature LCP thermoplastic with g.f, UL94v-0, Color: Black

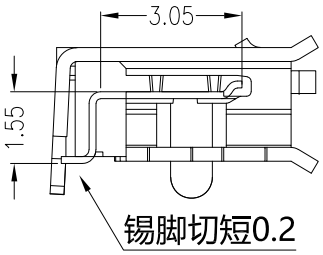
1.2 Contact: copper alloy,t=0.15mm
3u" MIN GOLD PLATED ON CONTACT AREA,
GOLD FLASH ON SOLDER TAILS,
30u"MIN NICKEL UNDERPLATING OVERALL. (C5191)

1.3 Shell: SUS304,t=0.30mm,
50u"MIN NICKEL PLATED OVER ALL.

2.Specification:

2.1 Current rating:1,5PIN 1.8A Max/2,3,4PIN 1A Max.
2.2 Dielectric withstanding voltage: 100 V(ac) for 1 min.
2.3 Contact resistance: 30 mΩ Max.
2.4 Insulation resistance: 100 MΩ Min.
2.5 Total mating force: 3.57 Kgf Max.
2.6 Total unmating force: 1.0 Kgf Min.
2.7 Temperature range: -40°C ~ +105°C
2.8 Durability:5000 Cycles





MATRIX PART NO:

MUSB 05 - 03 - 755

- MUSB: Matrix-USB
- 05: Pin number
- 03: Gold Plating: 01=Gold Flash(1u" Min), 03=3u", 30=30u"
- 755: Series Number

Matrix Electronics Co.,Ltd

TOLERANCE: X. ±0.30, X.X ±0.20, X.XX ±0.10, X.XXX, ANGLE: ±3°	DESIGN BY : Ken Lin	DATE : 2022/11/02	PART NAME: MICRO USB B/F DIP
	CHECKED BY: Vicky Hsieh	DATE : 2022/11/02	PART NO. MUSB05-03-755
UNIT: mm [inch]	APPROVED BY1: Richard Hsieh	DATE : 2022/11/02	MOLD NO. NA
SCALE:1:1 SIZE:A4	APPROVED BY2: Richard Hsieh	DATE : 2022/11/02	DRAW NO. / SHEET NO. 1 OF 1